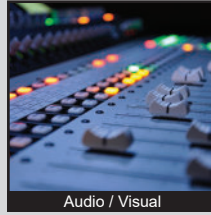


TL6800 SERIES TACT SWITCH

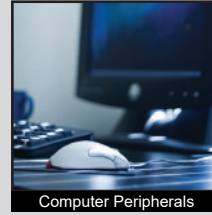
ANTI-VANDAL SWITCHES
DETECTOR SWITCHES
DIP SWITCHES
KEYLOCK SWITCHES
NAVIGATION SWITCHES
PUSHBUTTON SWITCHES
ROCKER SWITCHES
ROTARY SWITCHES
SLIDE SWITCHES
SNAP ACTION SWITCHES
TACTILE SWITCHES
TOGGLE SWITCHES
CAP OPTIONS



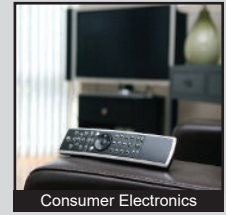
APPLICATIONS / MARKETS



Audio / Visual



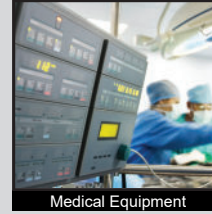
Computer Peripherals



Consumer Electronics



Instrumentation



Medical Equipment



Telecommunication

RoHS

SPECIFICATIONS

Electrical Rating: 50mA, 12VDC
Contact Resistance: 100mΩ Max. (Initial)
Insulation Resistance: 100MΩ Min. at 100VDC
Dielectric Strength: 250VAC for 1 Minute
Operating Temperature: -40°C to 90°C
Storage Temperature: -40°C to 90°C
Travel: 0.25mm +0.15mm
Moisture Protection: IP67
Actuation Force/Life Cycles: 160gf ±50gf/1,000,000 cycles
260gf ±50gf/500,000 cycles

Function: SPST, Off-(On)
Bounce: 10msec Max.
Contact Material: Silver
Packaging: Tape and Reel, 1,500 pcs/reel

FEATURES & BENEFITS

- Up to 1,000,000 cycle life expectancy
- Tape and Reel packaging
- Surface mount design
- Actuation force options
- IP67 Rating

PART NUMBER CONFIGURATOR

Series	Actuator	Actuation Force	Contact Material	Termination
<input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/>	<input type="text"/>	<input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/>	<input type="text"/>	<input type="text"/>
TL6800	A - 3.1mm	F160 - 160 gf - Brown F260 - 260 gf - Red	Q - Silver	J - J-bend

Specifications subject to change without notice 8.17.2022



E-SWITCH®

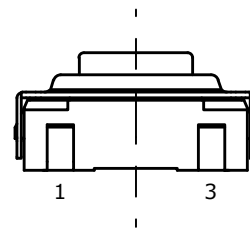
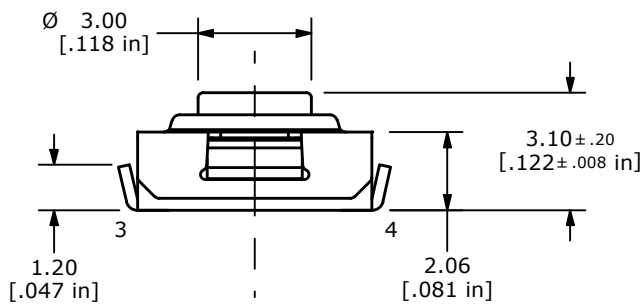
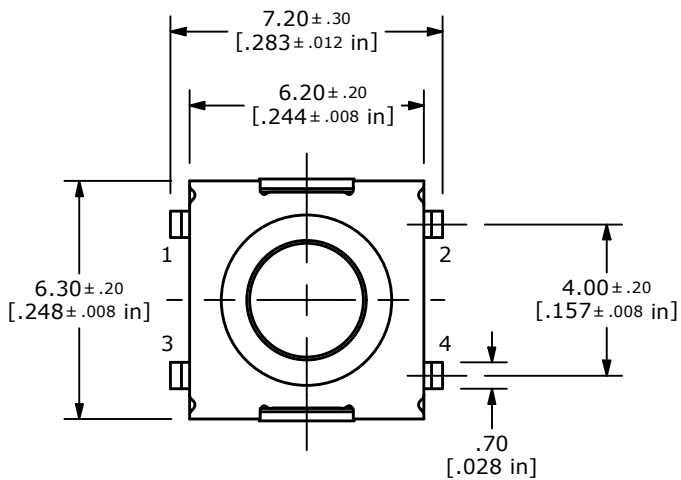
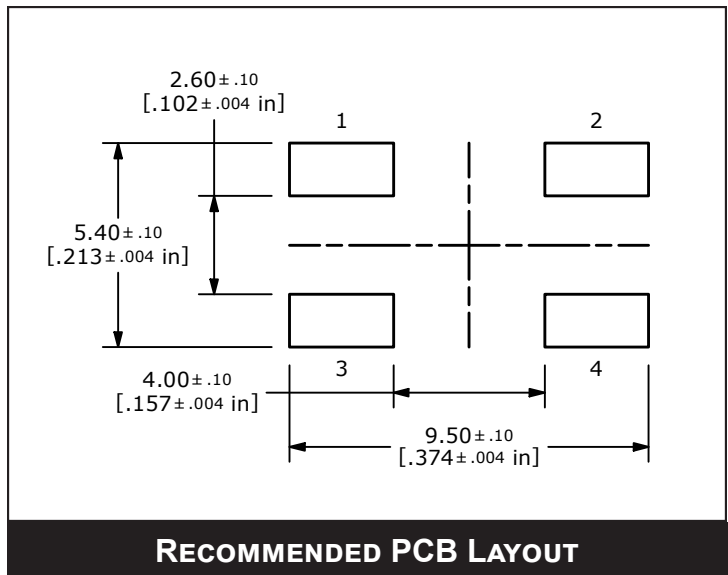
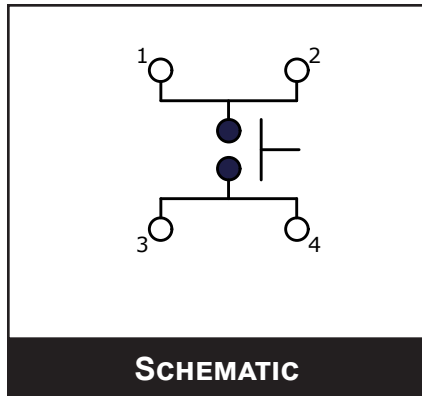
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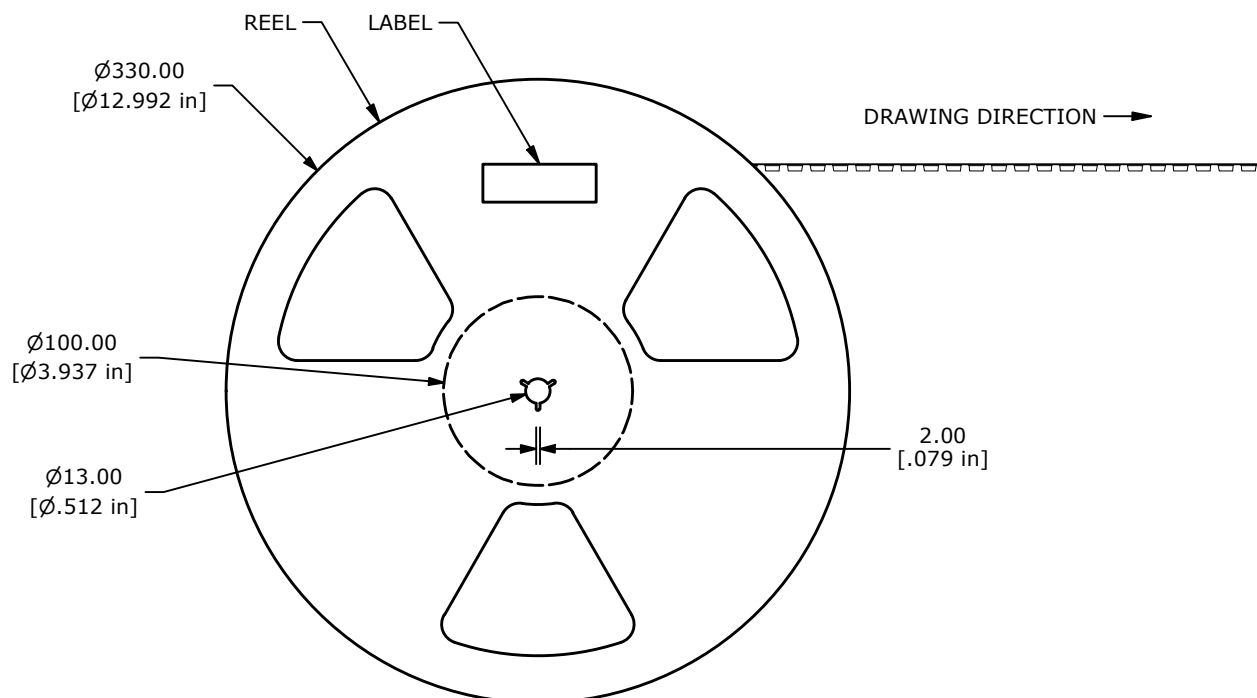
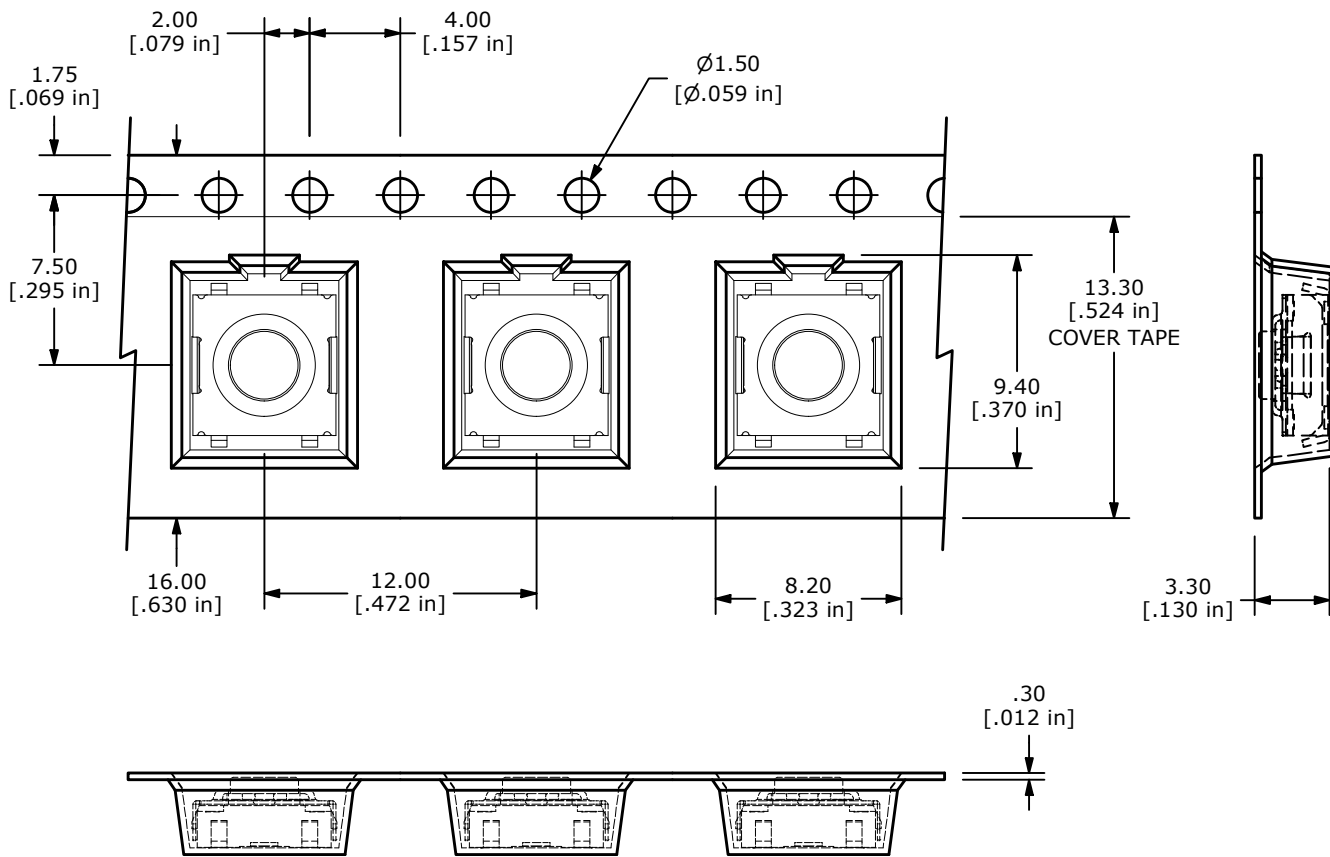
TL6800 SERIES TACT SWITCH

BODY DIMENSIONS



TL6800 SERIES TACT SWITCH

BODY DIMENSIONS TAPE AND REEL



RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C/second max.	3 °C/second max.
Preheat		
-Temperature Min ($T_{s_{min}}$)	100 °C	150 °C
-Temperature Max ($T_{s_{max}}$)	150 °C	200 °C
-Time ($t_{s_{min}}$ to $t_{s_{max}}$)	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature (T_L)	183 °C	217 °C
-Time (t_L)	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

